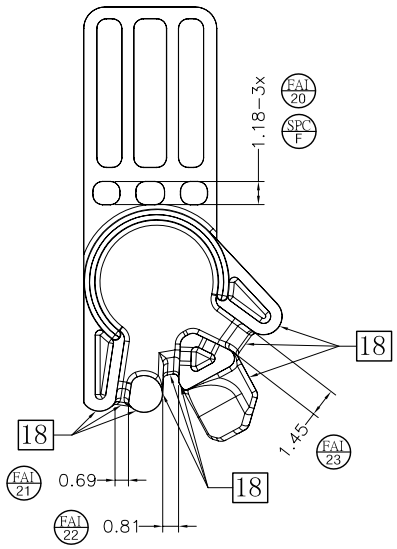
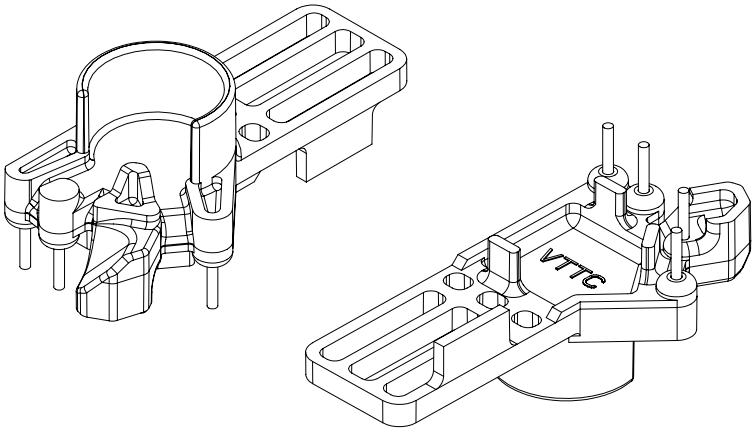
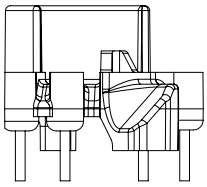
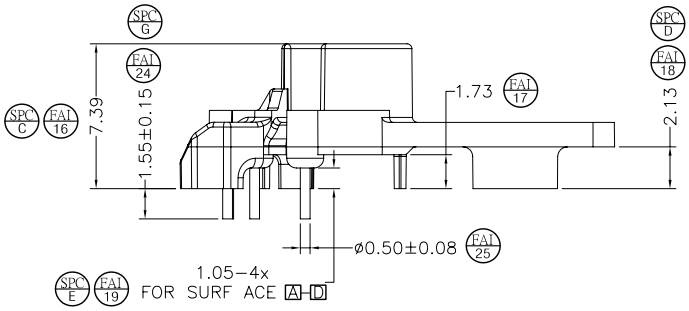
TBI TRANSFORMER BOBBIN INDUSTRIAL CO.,LTD.
Tel : 86-769-88789999 Fax : 86-769-88789989
http:// tbi-tw.com e-mail : tb6688@ms46.hinet.net

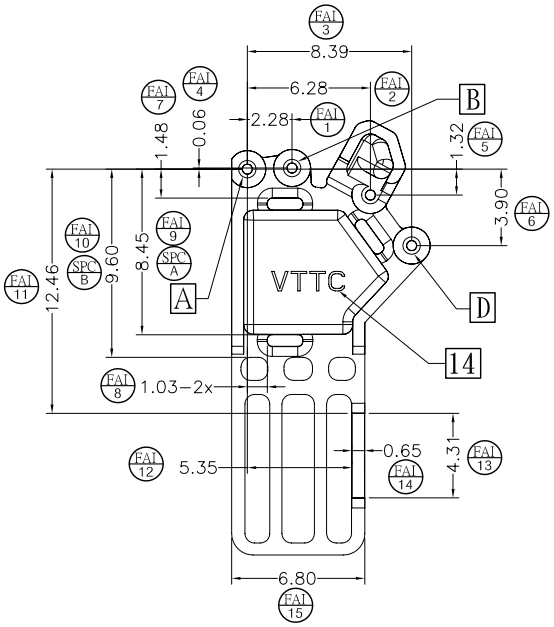
REVISIONS				
REV	SYM	DRAFTER	CHECKER	DATE
1		X.H.GU	G.F.YANG	05/29/12
2				
3				











1) Pin Material:1/2 or 3/4 hard copper platter(C.P.)
2) Platting:5.0um min matt TIN platting(Sn>99.9 %)
3) Tolerances designated with the symbol (SPC) shall be produced with statistical tolerance process controls.
In order to use the tolerance on a ature,the statistical process(Cpk,Cp etc) of the part must be validated and approved by Cooper.
4) Dimensions marked with (FAI) are to be used for process control.
5) All unspercified draft to be 0.5°.
6) Parting line mismatch not to exceed 0.10mm.
7) Flash not to exceed 0.10mm.
8) Gate vestige or trim not to exceed 0.10mm.
9) 0% regrind permissable.
10) Ejector pin marks must be flush with or no more than 0.10mm below surface of part.
11) Part to be free of mold release on cosmetic surfaces and glue geometry.
12) Part to be clean and free of contaminants upon delivery to final assembly vendor.
13) Radius all internal sharp coners to 0.25mm.
14) Tool markings for "V" (vendor),"TT" (tool number),and "C" (cavity).
15) Pin tolerance:±0.08mm.
16) Environmental substances requirement:
(a):RoHS compliance 2002/95 /EC, (b):PFOS & PFOA compliance 2006 /122 /EC,
(c):Halogen compliance:C1<900ppm,Br<900pm,C1+B1<1500ppm.
17) Pin pulling force>0.8Kg min after soldering(300±10°C/1Sec).
18) 0.05mm max.flash on these edges check 1 unit/caivty/every 4 hours. Can't use parts from cavity if out of spec.
19) Steam precondition 8 hours ±15 min,the surface area of pin is more than95 % after soldering(@255±5°C/5+0/-0.5Sec).

DWG NO.	B6B-4P-TH-A4-75					
PART NO.	MATERIAL (BOBBIN)	MATERIAL (TERMINAL)	TERMINAL (PLATING)	PIN ALLOCATION	NOTE	
TBI-220-22141.7506	FR52G30NH(BK)	CP WIRE	Sn	ALL PIN		S
						H
	TOLERANCE: 0<L<=4: ±0.1 4<L<=16: ±0.2 16<L<=: ±0.3 Pin pitch:±0.2			UNIT : m / m	SCALE 1 : 1	

Finish: 1. PB wire Immersion Sn on terminal : Thickness:Sn plating,100,5 μm (200 μinches) min,Base nickel 0.625 μm (25 μ inches) min.
2. CP wire Immersion Sn on terminal : Thickness:Sn plating,100,5 μm (200 μinches) min.
3. Coplanarity deviation: 0.10 mm (0.004 inches)max.

REV 1